## ABSTRACT OF THE DISCLOSURE

A surface acoustic wave device includes a surface acoustic wave element and an electronic component package for supporting the surface acoustic wave element. The surface acoustic wave element includes a piezoelectric substrate that has interdigital electrodes and electrode pads thereon. The electrode pads input and output electrical signals to and from the respective interdigital electrodes. The electronic component package has electrode pattern sections for inputting and outputting electrical signals. The surface acoustic wave device further includes metal bump connections for electrically connecting between the electrode pads and the respective electrode pattern sections. The electrode pads include aluminum as the major component and copper as a minor component, the copper content being at least about 3.5 percent by weight. To connect the electrode pads to the respective electrode pattern sections, the metal bump connections are formed by a flip chip process using ultrasonic waves.